Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP Chromebook 11 G8 Education Edition

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm M/B, D/B USB, Clickpad Module</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
</tbody>
</table>
| Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.) | Battery(ies) are attached to the product by *(check all that apply with an “x” inside the “[ ]”)*: [x] screws [0] snaps [0] adhesive [ ] other. Explain ____.

NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2. |
|                                                                                   |                                                                                                 | 1                                    |
| Mercury-containing components                                                    | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries         |                                      |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm             | Includes background illuminated displays with gas discharge lamps 11.6”                       | 1                                    |
| Cathode Ray Tubes (CRT)                                                         |                                                                                                 |                                      |
| Capacitors / condensers (Containing PCB/PCT)                                    |                                                                                                 |                                      |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height |                                                                                                 |                                      |
| External electrical cables and cords                                           | DC Cable for External Power Supply                                                                | 1                                    |
| Gas Discharge Lamps                                                             |                                                                                                 |                                      |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs) |                                                                                                 |                                      |

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure: Remove base screws.

1. Remove hinge cap.
2. Release base screws.
5. Release Batt. screws, remove Batt.
6. Release adaptor cable & FFC & screws, remove USB type C bracket & D/B
8. Remove LCD bezel.
9. Release panel support Bkt. & screws.
10. Release LCD cable, remove panel.
11. Release hinge screws, remove hinges.
12. Remove Cam. module & LCD cable & Cam. cable & antenna from LCD cover Assy.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

HPI instructions for this template are available at EL-MF877-01
1. Remove hinge cap.

2. Release base screws.


5. Release Batt. screws, remove Batt.

6. Release adaptor cable & FFC & screws, remove USB type C bracket & D/B


EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
8. Remove LCD bezel.

9. Release panel support Bkt. & screws.

10. Release LCD cable, remove panel.

HPI instructions for this template are available at EL-MF877-01
11. Release hinge screws, remove hinges.

12. Remove Cam. module & LCD cable & Cam. cable & antenna from LCD cover Assy.